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WHAT IS CLAIMED IS:

An optical module comprising:

an optical semiconductor element sealed with a cap having an upper surface formed with a window;

at least one optical part confronted with the window;

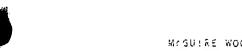
a housing holding the optical part therein, and having an opened end face; and

a connecting layer directly connecting the upper surface of the cap to the opened end face of the housing.

- The optical module according to claim 1, wherein an outer dimension of the opened end face of the housing is equal to or smaller than an outer dimension of the upper surface of the cap.
- The optical module according to claim 1, wherein the 3. optical semiconductor element has a stem portion opposite from the upper surface of the cap, and an outer dimension of the opened end face of the housing is equal to or smaller than an outer dimension of the stem portion.
- The optical module according to claim 1, wherein the optical semiconductor element has a stem portion opposite from 20 the upper surface of the cap, and the stem portion is distanced from the opened end face of the housing.
 - The optical module according to claim 1, wherein the 5. connecting layer is formed by an adhesive curable by irradiation of ultraviolet rays.

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- 6. The optical module according to claim 1, wherein the housing has a receptacle part adapted to receive a mating optical plug.
- 7. The optical module according to claim 1, further5 comprising:

a casing, which at least partly covers the cap and the housing; and which extends across the connecting layer.

- 8. The optical module according to claim 7, further comprising:
- a sealing layer filled in a clearance between the casing, and the connecting layer, the sealing layer being formed by resin curable thermally.
- 9. An optical module in which an optical semiconductor element of the cap sealing type is mounted on a housing to be aligned with an optical axis of at least one optical part contained in the housing, wherein:

an upper surface of a cap of said optical semiconductor element is bonded to an end face of said housing.

10. An optical module in which an optical semiconductor element of the cap sealing type is mounted on a housing to be aligned with an optical axis of a lens contained in the housing adapted to fittingly receive and hold a ferule of an optical plug of an mating connecting member, wherein:

an upper surface of a cap of said optical semiconductor element is bonded to an end face of said housing.



sub		11. The optical module according to claim 9 or 10, wherein
A١		a side surface of said cap of said optical semiconductor element
		and a side surface of said housing is at least partly covered
		with a casing, and a clearance therebetween is sealed with resin.
	5	12. The optical module according to claim 11, wherein the
		upper surface of said cap of said optical semiconductor element
		and the end face of said housing are bonded by ultraviolet curing
		adhesive, and the clearance between the inner surface of said
		casing, and each of the side surface of said cap of said optical
	10	semiconductor element and the side surface of said housing is
		sealed with thermosetting resin.
SuP I		13. An optical module unit wherein a plurality of the optical
AAÜ		modules constructed according to claim 9 or 10 are arrayed in
		juxtaposition, and covered with a single common casing, and a
	15	clearance therebetween is sealed with resin.
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